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Details

E·XF

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I ² C, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, I ² S, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	66KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f5011-20i-pt

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.0 DEVICE OVERVIEW

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046). For more information on the device instruction set and programming, refer to the "16-bit MCU and DSC Programmer's Reference Manual" (DS70157).

This document contains specific information for the dsPIC30F5011/5013 Digital Signal Controller (DSC) devices. The dsPIC30F5011/5013 devices contain extensive Digital Signal Processor (DSP) functionality within a high-performance 16-bit microcontroller (MCU) architecture. Figure 1-1 and Figure 1-2 show device block diagrams for dsPIC30F5011 and dsPIC30F5013, respectively.

Pin Name	Pin Type	Buffer Type	Description
OSC1	I	ST/CMOS	Oscillator crystal input. ST buffer when configured in RC mode;
OSC2	I/O	—	CMOS otherwise. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
PGD	I/O	ST	In-Circuit Serial Programming™ data input/output pin.
PGC	I	ST	In-Circuit Serial Programming clock input pin.
RA6-RA7	I/O	ST	PORTA is a bidirectional I/O port.
RA9-RA10	I/O	ST	
RA12-RA15	I/O	ST	
RB0-RB15	I/O	ST	PORTB is a bidirectional I/O port.
RC1-RC4	I/O	ST	PORTC is a bidirectional I/O port.
RC13-RC15	I/O	ST	
RD0-RD15	I/O	ST	PORTD is a bidirectional I/O port.
RF0-RF8	I/O	ST	PORTF is a bidirectional I/O port.
RG0-RG3	I/O	ST	PORTG is a bidirectional I/O port.
RG6-RG9	I/O	ST	
RG12-RG15	I/O	ST	
SCK1	I/O	ST	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	SPI1 Data In.
SDO1	0		SPI1 Data Out.
SS1		SI	SPI1 Slave Synchronization.
	1/0	ST	SPI2 Data In
SDO2	0		SPI2 Data M.
SS2		ST	SPI2 Slave Synchronization.
SCL	I/O	ST	Synchronous serial clock input/output for I ² C™.
SDA	I/O	ST	Synchronous serial data input/output for I ² C.
SOSCO	0	_	32 kHz low-power oscillator crystal output.
SOSCI	I	ST/CMOS	32 kHz low-power oscillator crystal input. ST buffer when
			configured in RC mode; CMOS otherwise.
T1CK	I	ST	Timer1 external clock input.
T2CK	I	ST	Timer2 external clock input.
13CK		SI	Timer3 external clock input.
TACK		SI	Timer4 external clock input.
TOCK	1		
		51	UARTI Receive.
	U U	ST	IIART1 Alternate Receive
U1ATX	Ö	_	UART1 Alternate Transmit.
U2RX	I	ST	UART2 Receive.
U2TX	0	_	UART2 Transmit.
Vdd	Р	_	Positive supply for logic and I/O pins.
Vss	Р	_	Ground reference for logic and I/O pins.
VREF+		Analog	Analog Voltage Reference (High) input.
VREF-		Analog	Analog Voltage Reference (Low) input.
Legend: Cl	MOS = CM	OS compatit	ble input or output Analog = Analog input
S	Γ = Sch	mitt Trigger	input with CMOS levels O = Output
I	= Inpu	ut	P = Power

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

The core does not support a multi-stage instruction pipeline. However, a single stage instruction prefetch mechanism is used, which accesses and partially decodes instructions a cycle ahead of execution, in order to maximize available execution time. Most instructions execute in a single cycle with certain exceptions.

The core features a vectored exception processing structure for traps and interrupts, with 62 independent vectors. The exceptions consist of up to 8 traps (of which 4 are reserved) and 54 interrupts. Each interrupt is prioritized based on a user assigned priority between 1 and 7 (1 being the lowest priority and 7 being the highest), in conjunction with a predetermined 'natural order'. Traps have fixed priorities ranging from 8 to 15.

2.2 Programmer's Model

The programmer's model is shown in Figure 2-1 and consists of 16 x 16-bit working registers (W0 through W15), 2 x 40-bit accumulators (AccA and AccB), STATUS register (SR), Data Table Page register (TBLPAG), Program Space Visibility Page register (PSVPAG), DO and REPEAT registers (DOSTART, DOEND, DCOUNT and RCOUNT) and Program Counter (PC). The working registers can act as data, address or offset registers. All registers are memory mapped. W0 acts as the W register for file register addressing.

Some of these registers have a shadow register associated with each of them, as shown in Figure 2-1. The shadow register is used as a temporary holding register and can transfer its contents to or from its host register upon the occurrence of an event. None of the shadow registers are accessible directly. The following rules apply for transfer of registers into and out of shadows.

- PUSH.S and POP.S W0, W1, W2, W3, SR (DC, N, OV, Z and C bits only) are transferred.
- DO instruction DOSTART, DOEND, DCOUNT shadows are pushed on loop start, and popped on loop end.

When a byte operation is performed on a working register, only the Least Significant Byte (LSB) of the target register is affected. However, a benefit of memory mapped working registers is that both the Least and Most Significant Bytes (MSBs) can be manipulated through byte wide data memory space accesses.

2.2.1 SOFTWARE STACK POINTER/ FRAME POINTER

The dsPIC[®] DSC devices contain a software stack. W15 is the dedicated software Stack Pointer (SP), and will be automatically modified by exception processing and subroutine calls and returns. However, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies the reading, writing and manipulation of the Stack Pointer (e.g., creating stack frames).

Note:	In order to protect against misaligned
	stack accesses, W15<0> is always clear.

W15 is initialized to 0x0800 during a Reset. The user may reprogram the SP during initialization to any location within data space.

W14 has been dedicated as a Stack Frame Pointer as defined by the LNK and ULNK instructions. However, W14 can be referenced by any instruction in the same manner as all other W registers.

2.2.2 STATUS REGISTER

The dsPIC DSC core has a 16-bit STATUS register (SR), the LSB of which is referred to as the SR Low byte (SRL) and the MSB as the SR High byte (SRH). See Figure 2-1 for SR layout.

SRL contains all the MCU ALU operation status flags (including the Z bit), as well as the CPU Interrupt Priority Level status bits, IPL<2:0> and the Repeat Active Status bit, RA. During exception processing, SRL is concatenated with the MSB of the PC to form a complete word value which is then stacked.

The upper byte of the STATUS register contains the DSP Adder/Subtracter status bits, the DO Loop Active bit (DA) and the Digit Carry (DC) Status bit.

2.2.3 PROGRAM COUNTER

The program counter is 23 bits wide; bit 0 is always clear. Therefore, the PC can address up to 4M instruction words.

TABLE 3-1: PROGRAM SPACE ADDRESS CONSTRUCTION

	Access	Program Space Address						
Access Type	Space	<23>	<22:16>	<15>	<14:1>	<0>		
Instruction Access	User	0		PC<22:1>		0		
TBLRD/TBLWT	User (TBLPAG<7> = 0)	TBL	PAG<7:0>		Data EA<15:0>			
TBLRD/TBLWT	Configuration (TBLPAG<7> = 1)	TBL	.PAG<7:0>		Data EA<15:0>			
Program Space Visibility	User	0	PSVPAG<	7:0>	Data EA<1	4:0>		

FIGURE 3-2: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



3.2.2 DATA SPACES

X data space is used by all instructions and supports all Addressing modes. There are separate read and write data buses. The X read data bus is the return data path for all instructions that view data space as combined X and Y address space. It is also the X address space data path for the dual operand read instructions (MAC class). The X write data bus is the only write path to data space for all instructions.

The X data space also supports modulo addressing for all instructions, subject to Addressing mode restrictions. Bit-reversed addressing is only supported for writes to X data space.

The Y data space is used in concert with the X data space by the MAC class of instructions (CLR, ED, EDAC, MAC, MOVSAC, MPY, MPY.N and MSC) to provide two concurrent data read paths. No writes occur across the Y bus. This class of instructions dedicates two W register pointers, W10 and W11, to always address Y data space, independent of X data space, whereas W8 and W9 always address X data space. Note that during accumulator write back, the data address space is considered a combination of X and Y data spaces, so the write occurs across the X bus. Consequently, the write can be to any address in the entire data space.

The Y data space can only be used for the data prefetch operation associated with the MAC class of instructions. It also supports modulo addressing for automated circular buffers. Of course, all other instructions can access the Y data address space through the X data path as part of the composite linear space.

The boundary between the X and Y data spaces is defined as shown in Figure 3-6 and is not user programmable. Should an EA point to data outside its own assigned address space, or to a location outside physical memory, an all zero word/byte will be returned. For example, although Y address space is visible by all non-MAC instructions using any Addressing mode, an attempt by a MAC instruction to fetch data from that space using W8 or W9 (X space pointers) will return 0x0000.

TABLE 3-2: EFFECT OF INVALID MEMORY ACCESSES

Attempted Operation	Data Returned
EA = an unimplemented address	0x0000
W8 or W9 used to access Y data space in a MAC instruction	0x0000
W10 or W11 used to access X data space in a MAC instruction	0x0000

All effective addresses are 16 bits wide and point to bytes within the data space. Therefore, the data space address range is 64 Kbytes or 32K words.

3.2.3 DATA SPACE WIDTH

The core data width is 16 bits. All internal registers are organized as 16-bit wide words. Data space memory is organized in byte addressable, 16-bit wide blocks.

3.2.4 DATA ALIGNMENT

To help maintain backward compatibility with PIC® MCU devices and improve data space memory usage efficiency, the dsPIC30F instruction set supports both word and byte operations. Data is aligned in data memory and registers as words, but all data space EAs resolve to bytes. Data byte reads will read the complete word which contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSB of the X data path (no byte accesses are possible from the Y data path as the MAC class of instruction can only fetch words). That is, data memory and registers are organized as two parallel byte wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register which matches the byte address.

As a consequence of this byte accessibility, all effective address calculations (including those generated by the DSP operations which are restricted to word sized data) are internally scaled to step through word aligned memory. For example, the core would recognize that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws+1 for byte operations and Ws+2 for word operations.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. Should a misaligned read or write be attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed, whereas if it occurred on a write, the instruction will be executed but the write will not occur. In either case, a trap will then be executed, allowing the system and/or user to examine the machine state prior to execution of the address fault.

FIGURE 3-8: DATA ALIGNMENT

	15 MSB 8	7 LSB	D
0001	Byte1	Byte 0	0000
0003	Byte3	Byte 2	0002
0005	Byte5	Byte 4	0004

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A sign-extend (SE) instruction is provided to allow users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions, including the DSP instructions, operate only on words.

3.2.5 NEAR DATA SPACE

An 8 Kbyte 'near' data space is reserved in X address memory space between 0x0000 and 0x1FFF, which is directly addressable via a 13-bit absolute address field within all memory direct instructions. The remaining X address space and all of the Y address space is addressable indirectly. Additionally, the whole of X data space is addressable using MOV instructions, which support memory direct addressing with a 16-bit address field.

3.2.6 SOFTWARE STACK

The dsPIC DSC devices contain a software stack. W15 is used as the Stack Pointer.

The Stack Pointer always points to the first available free word and grows from lower addresses towards higher addresses. It pre-decrements for stack pops and post-increments for stack pushes as shown in Figure 3-9. Note that for a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, ensuring that the MSB is always clear.

Note: A PC push during exception processing will concatenate the SRL register to the MSB of the PC prior to the push.

There is a Stack Pointer Limit register (SPLIM) associated with the Stack Pointer. SPLIM is uninitialized at Reset. As is the case for the Stack Pointer, SPLIM<0> is forced to '0' because all stack operations must be word aligned. Whenever an effective address (EA) is generated using W15 as a source or destination pointer, the address thus generated is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal and a push operation is performed, a Stack Error Trap will not occur. The Stack Error Trap will occur on a subsequent push operation. Thus, for example, if it is desirable to cause a Stack Error Trap when the stack grows beyond address 0x2000 in RAM, initialize the SPLIM with the value 0x1FFE.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be less than 0x0800, thus preventing the stack from interfering with the Special Function Register (SFR) space.

A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.

FIGURE 3-9: CALL STACK FRAME



3.2.7 DATA RAM PROTECTION FEATURE

The dsPIC30F5011/5013 devices support data RAM protection features which enable segments of RAM to be protected when used in conjunction with Boot and Secure Code Segment Security. BSRAM (Secure RAM segment for BS) is accessible only from the Boot Segment Flash code when enabled. SSRAM (Secure RAM segment for RAM) is accessible only from the Secure Segment Flash code when enabled. See Table 3-3 for the BSRAM and SSRAM SFRs.

dsPIC30F5011/5013

NOTES:

9.0 TIMER1 MODULE

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046).

This section describes the 16-bit General Purpose (GP) Timer1 module and associated operational modes. Figure 9-1 depicts the simplified block diagram of the 16-bit Timer1 module.

The following sections provide a detailed description including setup and control registers, along with associated block diagrams for the operational modes of the timers.

The Timer1 module is a 16-bit timer that can serve as the time counter for the real-time clock or operate as a free-running interval timer/counter. The 16-bit timer has the following modes:

- 16-bit Timer
- 16-bit Synchronous Counter
- · 16-bit Asynchronous Counter

Further, the following operational characteristics are supported:

- Timer gate operation
- · Selectable prescaler settings
- Timer operation during CPU Idle and Sleep modes
- Interrupt on 16-bit Period register match or falling edge of external gate signal

These operating modes are determined by setting the appropriate bit(s) in the 16-bit SFR, T1CON. Figure 9-1 presents a block diagram of the 16-bit timer module.

16-bit Timer Mode: In the 16-bit Timer mode, the timer increments on every instruction cycle up to a match value preloaded into the Period register PR1, then resets to '0' and continues to count.

When the CPU goes into the Idle mode, the timer will stop incrementing unless the TSIDL (T1CON<13>) bit = 0. If TSIDL = 1, the timer module logic will resume the incrementing sequence upon termination of the CPU Idle mode.

16-bit Synchronous Counter Mode: In the 16-bit Synchronous Counter mode, the timer increments on the rising edge of the applied external clock signal which is synchronized with the internal phase clocks. The timer counts up to a match value preloaded in PR1, then resets to '0' and continues.

When the CPU goes into the Idle mode, the timer will stop incrementing unless the respective TSIDL bit = 0. If TSIDL = 1, the timer module logic will resume the incrementing sequence upon termination of the CPU Idle mode.

16-bit Asynchronous Counter Mode: In the 16-bit Asynchronous Counter mode, the timer increments on every rising edge of the applied external clock signal. The timer counts up to a match value preloaded in PR1, then resets to '0' and continues.

When the timer is configured for the Asynchronous mode of operation and the CPU goes into the Idle mode, the timer will stop incrementing if TSIDL = 1.





I²C REGISTER MAP⁽¹⁾ **TABLE 15-2**:

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State	
I2CRCV	0200	Ι	1	Ι		1		1					Receive R	egister				0000 0000 0000 0000	
I2CTRN	0202	Ι	Ι	I	Ι	I		I	I				Transmit R	egister				0000 0000 1111 1111	
12CBRG	0204	Ι	Ι	I	Ι	I						Baud R	ate Genera	ator				0000 0000 0000 0000	
I2CCON	0206	I2CEN	Ι	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0001 0000 0000 0000	
I2CSTAT	0208	ACKSTAT	TRSTAT	Ι	Ι	Ι	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	٩	s	R_W	RBF	TBF	0000 0000 0000 0000	
12CADD	020A	Ι	Ι	Ι	Ι	Ι					,	Address R	egister					0000 0000 0000 0000	
- 00000	I	implementee	, 00 000 1	,0															

 — = unimplemented, read as '0'
 Refer to "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.
 Legend: Note 1:

16.9 Auto Baud Support

To allow the system to determine baud rates of received characters, the input can be optionally linked to a capture input (IC1 for UART1, IC2 for UART2). To enable this mode, the user must program the input capture module to detect the falling and rising edges of the Start bit.

16.10 UART Operation During CPU Sleep and Idle Modes

16.10.1 UART OPERATION DURING CPU SLEEP MODE

When the device enters Sleep mode, all clock sources to the module are shutdown and stay at logic '0'. If entry into Sleep mode occurs while a transmission is in progress, then the transmission is aborted. The UxTX pin is driven to logic '1'. Similarly, if entry into Sleep mode occurs while a reception is in progress, then the reception is aborted. The UxSTA, UxMODE, transmit and receive registers and buffers, and the UxBRG register are not affected by Sleep mode.

If the WAKE bit (UxMODE<7>) is set before the device enters Sleep mode, then a falling edge on the UxRX pin will generate a receive interrupt. The Receive Interrupt Select mode bit (URXISEL) has no effect for this function. If the receive interrupt is enabled, then this will wake-up the device from Sleep. The UARTEN bit must be set in order to generate a wake-up interrupt.

16.10.2 UART OPERATION DURING CPU IDLE MODE

For the UART, the USIDL bit selects if the module will stop operation when the device enters Idle mode or whether the module will continue on Idle. If USIDL = 0, the module will continue operation during Idle mode. If USIDL = 1, the module will stop on Idle.

18.3 DCI Module Operation

18.3.1 MODULE ENABLE

The DCI module is enabled or disabled by setting/ clearing the DCIEN control bit in the DCICON1 SFR. Clearing the DCIEN control bit has the effect of resetting the module. In particular, all counters associated with CSCK generation, frame sync and the DCI buffer control unit are Reset.

The DCI clocks are shutdown when the DCIEN bit is cleared.

When enabled, the DCI controls the data direction for the four I/O pins associated with the module. The Port, LAT and TRIS register values for these I/O pins are overridden by the DCI module when the DCIEN bit is set.

It is also possible to override the CSCK pin separately when the bit clock generator is enabled. This permits the bit clock generator to operate without enabling the rest of the DCI module.

18.3.2 WORD SIZE SELECTION BITS

The WS<3:0> word size selection bits in the DCICON2 SFR determine the number of bits in each DCI data word. Essentially, the WS<3:0> bits determine the counting period for a 4-bit counter clocked from the CSCK signal.

Any data length, up to 16-bits, may be selected. The value loaded into the WS<3:0> bits is one less the desired word length. For example, a 16-bit data word size is selected when WS<3:0> = 1111.

Note:	These WS<3:0> control bits are used only in the Multi-Channel and I ² S modes. These
	bits have no effect in AC-Link mode since the data slot sizes are fixed by the protocol.

18.3.3 FRAME SYNC GENERATOR

The frame sync generator (COFSG) is a 4-bit counter that sets the frame length in data words. The frame sync generator is incremented each time the word size counter is reset (refer to **Section 18.3.2** "**Word Size Selection Bits**"). The period for the frame synchronization generator is set by writing the COFSG<3:0> control bits in the DCICON2 SFR. The COFSG period in clock cycles is determined by the following formula:

EQUATION 18-1: COFSG PERIOD

 $Frame Length = Word Length \bullet (FSG Value + 1)$

Frame lengths, up to 16 data words, may be selected. The frame length in CSCK periods can vary up to a maximum of 256 depending on the word size that is selected.

Note: The COFSG control bits will have no effect in AC-Link mode since the frame length is set to 256 CSCK periods by the protocol.

18.3.4 FRAME SYNC MODE CONTROL BITS

The type of frame sync signal is selected using the Frame Synchronization mode control bits (COFSM<1:0>) in the DCICON1 SFR. The following operating modes can be selected:

- Multi-Channel mode
- I²S mode
- AC-Link mode (16-bit)
- AC-Link mode (20-bit)

The operation of the COFSM control bits depends on whether the DCI module generates the frame sync signal as a master device, or receives the frame sync signal as a slave device.

The master device in a DSP/codec pair is the device that generates the frame sync signal. The frame sync signal initiates data transfers on the CSDI and CSDO pins and usually has the same frequency as the data sample rate (COFS).

The DCI module is a frame sync master if the COFSD control bit is cleared and is a frame sync slave if the COFSD control bit is set.

18.3.5 MASTER FRAME SYNC OPERATION

When the DCI module is operating as a frame sync master device (COFSD = 0), the COFSM mode bits determine the type of frame sync pulse that is generated by the frame sync generator logic.

A new COFS signal is generated when the frame sync generator resets to '0'.

In the Multi-Channel mode, the frame sync pulse is driven high for the CSCK period to initiate a data transfer. The number of CSCK cycles between successive frame sync pulses will depend on the word size and frame sync generator control bits. A timing diagram for the frame sync signal in Multi-Channel mode is shown in Figure 18-2.

In the AC-Link mode of operation, the frame sync signal has a fixed period and duty cycle. The AC-Link frame sync signal is high for 16 CSCK cycles and is low for 240 CSCK cycles. A timing diagram with the timing details at the start of an AC-Link frame is shown in Figure 18-3.

In the l^2S mode, a frame sync signal having a 50% duty cycle is generated. The period of the l^2S frame sync signal in CSCK cycles is determined by the word size and frame sync generator control bits. A new l^2S data transfer boundary is marked by a high-to-low or a low-to-high transition edge on the COFS pin.

18.3.6 SLAVE FRAME SYNC OPERATION

When the DCI module is operating as a frame sync slave (COFSD = 1), data transfers are controlled by the codec device attached to the DCI module. The COFSM control bits control how the DCI module responds to incoming COFS signals.

18.3.7 BIT CLOCK GENERATOR

The DCI module has a dedicated 12-bit time base that produces the bit clock. The bit clock rate (period) is set by writing a non-zero 12-bit value to the BCG<11:0> control bits in the DCICON3 SFR.

When the BCG<11:0> bits are set to zero, the bit clock will be disabled. If the BCG<11:0> bits are set to a nonzero value, the bit clock generator is enabled. These bits should be set to '0' and the CSCKD bit set to '1' if the serial clock for the DCI is received from an external device.

The formula for the bit clock frequency is given in Equation 18-2.

EQUATION 18-2: BIT CLOCK FREQUENCY

$$FBCK = \frac{FCY}{2 \bullet (BCG + 1)}$$

The required bit clock frequency will be determined by the system sampling rate and frame size. Typical bit clock frequencies range from 16x to 512x the converter sample rate depending on the data converter and the communication protocol that is used.

To achieve bit clock frequencies associated with common audio sampling rates, the user will need to select a crystal frequency that has an 'even' binary value. Examples of such crystal frequencies are listed in Table 18-1.

Fs (ĸHz)	Fcsck/Fs	Fcscк (MHz) ⁽¹⁾	Fosc (MHz)	PLL	FCYC (MIPS)	BCG ⁽²⁾
8	256	2.048	8.192	4	8.192	1
12	256	3.072	6.144	8	12.288	1
32	32	1,024	8.192	8	16.384	7
44.1	32	1.4112	5.6448	8	11.2896	3
48	64	3.072	6.144	16	24.576	3

TABLE 18-1: DEVICE FREQUENCIES FOR COMMON CODEC CSCK FREQUENCIES

Note 1: When the CSCK signal is applied externally (CSCKD = 1), the external clock high and low times must meet the device timing requirements.

2: When the CSCK signal is applied externally (CSCKD = 1), the BCG<11:0> bits have no effect on the operation of the DCI module.

20.2 Oscillator Configurations

20.2.1 INITIAL CLOCK SOURCE SELECTION

While coming out of Power-on Reset or Brown-out Reset, the device selects its clock source based on:

- FOS<1:0> Configuration bits, which select one of four oscillator groups, and
- FPR<3:0> Configuration bits, which select one of 13 oscillator choices within the primary group

Table 20-2 shows the Configuration bit values for clock selection.

Oscillator Mode	Oscillator Source	FOS1	FOS0	FPR3	FPR2	FPR1	FPR0	OSC2 Function
EC	Primary	1	1	1	0	1	1	CLKO
ECIO	Primary	1	1	1	1	0	0	I/O
EC w/ PLL 4x	Primary	1	1	1	1	0	1	I/O
EC w/ PLL 8x	Primary	1	1	1	1	1	0	I/O
EC w/ PLL 16x	Primary	1	1	1	1	1	1	I/O
ERC	Primary	1	1	1	0	0	1	CLKO
ERCIO	Primary	1	1	1	0	0	0	I/O
XT	Primary	1	1	0	1	0	0	OSC2
XT w/ PLL 4x	Primary	1	1	0	1	0	1	OSC2
XT w/ PLL 8x	Primary	1	1	0	1	1	0	OSC2
XT w/ PLL 16x	Primary	1	1	0	1	1	1	OSC2
XTL	Primary	1	1	0	0	0	0	OSC2
FRC w/ PLL 4x	Internal FRC	1	1	0	0	0	1	I/O
FRC w/ PLL 8x	Internal FRC	1	1	1	0	1	0	I/O
FRC w/ PLL 16x	Internal FRC	1	1	0	0	1	1	I/O
HS	Primary	1	1	0	0	1	0	OSC2
LP	Secondary	0	0	—	—	—	—	(Notes 1, 2)
FRC	Internal FRC	0	1	Х	Х	Х	Х	(Notes 1, 2)
LPRC	Internal LPRC	1	0		_			(Notes 1, 2)

TABLE 20-2: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Note 1: OSC2 pin function is determined by the Primary Oscillator mode selection (FPR<3:0>).

2: OSC1 pin cannot be used as an I/O pin even if the secondary oscillator or an internal clock source is selected at all times.

20.2.2 OSCILLATOR START-UP TIMER (OST)

To ensure that a crystal oscillator (or ceramic resonator) has started and stabilized, an Oscillator Start-up Timer is included. It is a simple 10-bit counter that counts 1024 Tosc cycles before releasing the oscillator clock to the rest of the system. The time-out period is designated as TOST. The TOST time is involved every time the oscillator has to restart (i.e., on POR, BOR and wake-up from Sleep). The Oscillator Start-up Timer is applied to the LP oscillator, XT, XTL, and HS modes (upon wake-up from Sleep, POR and BOR) for the primary oscillator.

20.2.3 LP OSCILLATOR CONTROL

Enabling the LP oscillator is controlled with two elements:

- The current oscillator group bits COSC<1:0>.
- The LPOSCEN bit (OSCON register).

The LP oscillator is on (even during Sleep mode) if LPOSCEN = 1. The LP oscillator is the device clock if:

- COSC<1:0> = 00 (LP selected as main oscillator) and
- LPOSCEN = 1

Keeping the LP oscillator on at all times allows for a fast switch to the 32 kHz system clock for lower power operation. Returning to the faster main oscillator still requires a start-up time.

21.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046). For more information on the device instruction set and programming, refer to the "16-bit MCU and DSC Programmer's Reference Manual" (DS70157).

The dsPIC30F instruction set adds many enhancements to the previous PIC[®] MCU instruction sets, while maintaining an easy migration from PIC MCU instruction sets.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word divided into an 8-bit opcode which specifies the instruction type, and one or more operands which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- · Bit-oriented operations
- · Literal operations
- DSP operations
- Control operations

Table 21-1 shows the general symbols used in describing the instructions.

The dsPIC30F instruction set summary in Table 21-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand which is typically a register 'Wb' without any address modifier
- The second source operand which is typically a register 'Ws' with or without an address modifier
- The destination of the result which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- · The file register specified by the value 'f'
- The destination, which could either be the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/ shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement may use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by the value of 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand which is a register 'Wb' without any address modifier
- The second source operand which is a literal value
- The destination of the result (only if not the same as the first source operand) which is typically a register 'Wd' with or without an address modifier

The ${\tt MAC}$ class of DSP instructions may use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- · The X and Y address space prefetch operations
- · The X and Y address space prefetch destinations
- · The accumulator write back destination

The other DSP instructions do not involve any multiplication, and may include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions may use some of the following operands:

- A program memory address
- The mode of the table read and table write instructions

All instructions are a single word, except for certain double word instructions, which were made double word instructions so that all the required information is available in these 48 bits. In the second word, the 8 Most Significant bits are '0's. If this second word is executed as an instruction (by itself), it will execute as a NOP.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all table reads and writes, and RETURN/RETFIE instructions, which are single-word instructions but take two or three cycles. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or twoword instruction. Moreover, double word moves require two cycles. The double word instructions execute in two instruction cycles.

Note:	For more deta	ils on the inst	ruction set,
	refer to the	"16-bit MCU	and DSC
	Programmer's	Reference	Manual"
	(DS70157).		

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
<n:m></n:m>	Register bit field
.b	Byte mode selection
.d	Double Word mode selection
.S	Shadow register select
.W	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+=2}
bit4	4-bit bit selection field (used in word addressed instructions) $\in \{015\}$
C, DC, N, OV, Z	MCU status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x00000x1FFF}
lit1	1-bit unsigned literal $\in \{0,1\}$
lit4	4-bit unsigned literal ∈ {015}
lit5	5-bit unsigned literal ∈ {031}
lit8	8-bit unsigned literal ∈ {0255}
lit10	10-bit unsigned literal $\in \{0255\}$ for Byte mode, $\{0:1023\}$ for Word mode
lit14	14-bit unsigned literal $\in \{016384\}$
lit16	16-bit unsigned literal $\in \{065535\}$
lit23	23-bit unsigned literal ∈ {08388608}; LSB must be 0
None	Field does not require an entry, may be blank
OA, OB, SA, SB	DSP status bits: AccA Overflow, AccB Overflow, AccA Saturate, AccB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512511}
Slit16	16-bit signed literal ∈ {-3276832767}
Slit6	6-bit signed literal ∈ {-1616}

TABLE 21-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
Wb	Base W register ∈ {W0W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd], [++Wd], [Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd], [++Wnd], [Wnd], [Wnd+Wb] }
Wm,Wn	Dividend, Divisor working register pair (direct addressing)
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4*W4,W5*W5,W6*W6,W7*W7}
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions ∈ {W4*W5,W4*W6,W4*W7,W5*W6,W5*W7,W6*W7}
Wn	One of 16 working registers ∈ {W0W15}
Wnd	One of 16 destination working registers ∈ {W0W15}
Wns	One of 16 source working registers ∈ {W0W15}
WREG	W0 (working register used in file register instructions)
Ws	Source W register ∈ { Ws, [Ws], [Ws++], [Ws], [++Ws], [Ws] }
Wso	Source W register ∈ { Wns, [Wns], [Wns++], [Wns], [++Wns], [Wns], [Wns+Wb] }
Wx	X data space prefetch address register for DSP instructions ∈ {[W8]+=6, [W8]+=4, [W8]+=2, [W8], [W8]-=6, [W8]-=4, [W8]-=2, [W9]+=6, [W9]+=4, [W9]+=2, [W9], [W9]-=6, [W9]-=4, [W9]-=2, [W9+W12],none}
Wxd	X data space prefetch destination register for DSP instructions \in {W4W7}
Wy	Y data space prefetch address register for DSP instructions ∈ {[W10]+=6, [W10]+=4, [W10]+=2, [W10], [W10]-=6, [W10]-=4, [W10]-=2, [W11]+=6, [W11]+=4, [W11]+=2, [W11], [W11]-=6, [W11]-=4, [W11]-=2, [W11+W12], none}
Wyd	Y data space prefetch destination register for DSP instructions ∈ {W4W7}

TABLE 21-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

TABLE 23-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHAR	ACTERIST	CS	Standard Opera (unless otherw Operating temp	ating Co ise state erature	onditions ed) -40°C ≤ -40°C ≤	:: 2.5V t લ ≦Ta ≤+85 ≦Ta ≤+12	o 5.5V °C for Ir 5°C for	ndustrial Extended
Param No.	Symbol	Character	istic	Min	Typ ⁽¹⁾	Max	Units	Conditions
BO10	VBOR	BOR Voltage ⁽²⁾ on VDD transition high to	BORV = 11 ⁽³⁾		—		V	Not in operating range
		low	BORV = 10	2.60		2.71	V	
			BORV = 01	4.10		4.40	V	
			BORV = 00	4.58		4.73	V	
BO15	VBHYS			_	5	_	mV	

Note 1: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized but not tested in manufacturing.

3: 11 values not in usable operating range.

TABLE 23-12: DC CHARACTERISTICS: PROGRAM AND EEPROM

DC CHA	RACTER	ISTICS	Standa (unless Operati	rd Oper s otherwing temp	ating Co vise state erature	nditions d) -40°C : -40°C :	s: 2.5V to 5.5V ≦TA ≤+85°C for Industrial ≤TA ≤+125°C for Extended
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
		Data EEPROM Memory ⁽²⁾					
D120	ED	Byte Endurance	100K	1M	_	E/W	-40° C ≤TA ≤+85°C
D121	VDRW	VDD for Read/Write	Vmin	_	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	0.8	2	2.6	ms	RTSP
D123	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated
D124	IDEW	IDD During Programming	—	10	30	mA	Row Erase
		Program FLASH Memory ⁽²⁾					
D130	Eр	Cell Endurance	10K	100K	—	E/W	-40° C ≤TA ≤+85°C
D131	Vpr	VDD for Read	VMIN	_	5.5	V	VMIN = Minimum operating voltage
D132	VEB	VDD for Bulk Erase	4.5		5.5	V	
D133	VPEW	VDD for Erase/Write	3.0		5.5	V	
D134	TPEW	Erase/Write Cycle Time	0.8	2	2.6	ms	RTSP
D135	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated
D137	IPEW	IDD During Programming	—	10	30	mA	Row Erase
D138	IEB	IDD During Programming	—	10	30	mA	Bulk Erase

Note 1: Data in "Typ" column is at 5V, 25°C unless otherwise stated.

2: These parameters are characterized but not tested in manufacturing.



FIGURE 23-16: SPI MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

TABLE 23-33: SPI MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

АС СНИ	ARACTERIS	TICS	Standar (unless Operatir	d Operat otherwis	ing Con e stated ature	ditions:) -40°C ≤⊺ -40°C ≤⊺	2.5V to 5.5V Ā ≤+85°C for Industrial Ā ≤+125°C for Extended
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур ⁽²⁾	Max	Units	Conditions
SP70	TscL	SCKx Input Low Time	30			ns	
SP71	TscH	SCKx Input High Time	30	_		ns	
SP72	TscF	SCKx Input Fall Time ⁽³⁾		10	25	ns	
SP73	TscR	SCKx Input Rise Time ⁽³⁾		10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time ⁽³⁾		_		ns	See Parameter DO32
SP31	TdoR	SDOx Data Output Rise Time ⁽³⁾		_	_	ns	See Parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	_	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	_	_	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	_	_	ns	
SP50	TssL2scH, TssL2scL	SSx↓to SCKx↑ or SCKx↓Input	120	—	_	ns	
SP51	TssH2doZ	SSx↑ to SDOx Output High-Impedance ⁽³⁾	10	_	50	ns	
SP52	TscH2ssH TscL2ssH	SSx after SCK Edge	1.5 Tcy +40	_		ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Assumes 50 pF load on all SPI pins.

	Overflow and Saturation	20
	Round Logic	21
	Write Back	21
Data	a Address Space	28
	Alignment	30
	Alignment (Figure)	30
	Effect of Invalid Memory Accesses (Table)	30
	MCU and DSP (MAC Class) Instructions Example	29
	Memory Map	28
	Near Data Space	31
	Software Stack	31
	Spaces	30
	Width	30
Data	a Converter Interface (DCI) Module	117
Data	EEPROM Memory	53
	Erasing	54
	Erasing, Block	54
	Erasing, Word	54
	Protection Against Spurious Write	56
	Reading	53
	Write Verify	56
	Writing	55
	Writing, Block	56
	Writing, Word	55
DC		164
	BOR	172
	Brown-out Reset	171
	I/O Pin Output Specifications	170
	Idle Current (IIDLE)	167
	Low-Voltage Detect	170
		1/1
	Operating Current (IDD)	165
		100
	Power-Down Current (IPD)	168
	Power-Down Current (IPD)	168 172
DOI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications	168 172 165
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module	168 172 165
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator	168 172 165 121
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames	168 172 165 121 123
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Control	168 172 165 121 123 117
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Data Alignment Buffer Data Alignment	168 172 165 121 123 117 117
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment Buffer Length Control COES Bin	168 172 165 121 123 117 117 123
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment Buffer Length Control COFS Pin CSCK Bin	168 172 165 121 123 117 123 117 123 117
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment Buffer Length Control COSP Pin CSCK Pin CSDL Bin	168 172 165 121 123 117 123 117 117 117
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment Buffer Length Control COSP Pin CSDI Pin CSDD Mode Bit	168 172 165 121 123 117 123 117 117 117 124
DCI	Power-Down Current (IPD) Program and EEPROM Temperature and Voltage Specifications Module Bit Clock Generator Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment Buffer Length Control COFS Pin CSCK Pin CSDI Pin CSDO Mode Bit CSDO Pin	168 172 165 121 123 117 123 117 123 117 117 124 117
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit.	168 172 165 121 123 117 123 117 117 124 117 124
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies	168 172 165 121 123 117 123 117 117 123 117 117 124 117 122
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table)	168 172 165 121 123 117 123 117 123 117 117 124 117 122 Jen- 121
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control COFS Pin CSCK Pin CSDI Pin CSDO Mode Bit CSDO Pin Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode	168 172 165 121 123 117 123 117 123 117 124 117 124 117 122 Jen- 121
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table). Digital Loopback Mode	168 172 165 121 123 117 123 117 123 117 124 117 124 117 122 Jen- 121 124 119
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator	168 172 165 121 123 117 123 117 123 117 124 117 124 117 122 µen- 121 124 119 119
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit CSDO Mode Bit CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Mode Control Bits	168 172 165 121 123 117 123 117 123 117 124 117 124 117 124 117 124 119 119
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit CSDO Mode Bit CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Mode Control Bits I/O Pins	168 172 165 121 123 117 123 117 123 117 124 117 124 117 124 117 124 119 119 119
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Mode Control Bits I/O Pins. Interruots	168 172 165 121 123 117 123 117 123 117 124 117 124 117 124 119 119 119 124
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Mode Control Bits I/O Pins Interrupts Interrupts	168 172 165 121 123 117 117 123 117 117 124 117 124 117 124 119 119 117 117 124
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit CSDO Mode Bit CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits I/O Pins Interrupts Interrupts Introduction	168 172 165 121 123 117 117 123 117 117 124 117 124 117 124 119 119 117 124 119 117
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits Interrupts. Introduction Master Frame Sync Operation. Operation	168 172 165 121 123 117 117 123 117 117 124 117 124 119 119 117 124 119 119
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits. I/O Pins. Interrupts. Introduction Master Frame Sync Operation. Operation During CPU Idle Mode	168 172 165 121 123 117 123 117 123 117 124 117 124 119 119 117 124 119 117 124 119 117 124 117 124 119 117 124 119 119 124 124 125 121 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 124 124 124 124 124 124 124 124 124 124
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits Interrupts. Interrupts. Interrupts. Introduction Master Frame Sync Operation. Operation During CPU Idle Mode Operation During CPU Idle Mode	168 172 165 121 123 117 123 117 123 117 124 117 124 119 119 117 124 119 117 124 119 117 124 117 124 119 119 117 124 119 119 119 124 121 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 124 124 117 124 119 124 119 124 119 124 119 124 119 124 119 124 119 119 119 119 119 119 119 119 119 11
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits. Interrupts. Interrupts. Interrupts. Interrupts. Introduction. Operation During CPU Idle Mode. Operation During CPU Sleep Mode. Receive Slot Enable Bits.	168 172 165 121 123 117 123 117 123 117 124 117 124 117 124 119 119 117 124 119 119 117 124 117 124 119 119 117 124 119 119 124 124 125 121 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 124 124 117 124 124 119 124 119 124 119 124 119 124 119 124 119 124 119 124 119 119 124 119 119 119 119 119 119 119 119 119 11
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDI Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Generator. Frame Sync Mode Control Bits. I/O Pins. Interrupts. Interrupts. Introduction. Master Frame Sync Operation. Operation During CPU Idle Mode. Operation During CPU Sleep Mode. Receive Slot Enable Bits. Receive Status Bits.	168 172 165 121 123 117 123 117 123 117 124 117 124 117 124 119 119 117 124 119 119 117 124 117 124 117 124 119 119 119 124 124 122 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 123 117 124 124 117 124 124 117 124 117 124 117 124 119 119 119 119 119 119 119 119 119 11
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits. I/O Pins. Interrupts. Interrupts. Interrupts. Introduction. Operation During CPU Idle Mode. Operation During CPU Idle Mode. Receive Status Bits. Receive Status Bits. Register Map.	168 172 165 121 123 117 117 123 117 117 124 117 124 117 124 119 119 117 124 119 119 117 124 117 124 119 119 119 124 124 123 124 123 124 124 125 125 125 125 125 125 125 125 125 125
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Generator Frame Sync Mode Control Bits. I/O Pins. Interrupts. Interrupts. Interrupts. Introduction. Master Frame Sync Operation. Operation During CPU Idle Mode. Operation During CPU Idle Mode. Receive Slot Enable Bits. Receive Status Bits. Register Map. Sample Clock Edge Control Bit.	168 172 165 121 123 117 123 117 124 117 124 117 124 117 124 119 119 117 124 117 124 119 119 117 124 117 124 119 119 119 124 122 123 124 123 124 124 125 125 124 125 125 125 125 125 125 125 125 125 125
DCI	Power-Down Current (IPD) Program and EEPROM. Temperature and Voltage Specifications Module Bit Clock Generator. Buffer Alignment with Data Frames Buffer Control. Buffer Data Alignment. Buffer Length Control. COFS Pin. CSCK Pin. CSDO Mode Bit. CSDO Mode Bit. CSDO Pin. Data Justification Control Bit. Device Frequencies for Common Codec CSCK Frequencies (Table) Digital Loopback Mode Enable. Frame Sync Generator Frame Sync Generator Frame Sync Generator Frame Sync Operation. Master Frame Sync Operation. Operation During CPU Idle Mode Operation During CPU Idle Mode. Receive Status Bits. Register Map. Sample Clock Edge Control Bit. Slave Frame Sync Operation.	168 172 165 121 123 117 123 117 124 117 124 117 124 117 124 119 119 117 124 119 119 117 124 117 124 117 124 119 119 119 124 124 123 117 124 121 123 117 124 124 125 121 123 117 123 117 124 124 125 124 125 125 126 127 127 127 127 127 127 127 127 127 127

Synchronous Data Transfers 122
Timing Characteristics
AC-Link Mode 188
Multichannel, I ² S Modes 186
Timing Requirements
AC-Link Mode 188
Multishannal J ² C Madaa
I ransmit Slot Enable Bits 122
Transmit Status Bits 123
Transmit/Receive Shift Register 117
Underflow Mode Control Bit 124
Word Size Selection Bits 119
Development Support 159
Device Configuration
Begister Man 150
Register Map
Device Configuration Registers
FBORPOR 148
FBS 148
FGS 148
FOSC
FSS 148
FWDT 148
Dischling the LIADT
Disabiling the UART 101
Divide Support
Instructions (Table) 18
DSP Engine
Multiplier
Dual Output Compare Match Mode
Continuous Pulse Mode 82
Single Dulee Mede
Siligle Fulse Mode
E
E
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 101 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 37
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 37 Type A, B and C Timer 181
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 181 Type A, B and C Timer 181 External Clock Timing Requirements 174
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 Trap Sources 37 External Clock Timing Characteristics 181 External Clock Timing Requirements 174 Type A Timer 181
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 37 External Clock Timing Requirements 174 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 181 External Clock Timing Requirements 174 Type B Timer 181
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 101 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 37 External Clock Timing Requirements 174 Type A, B and C Timer 181 Type A Timer 182 Type C Timer 182
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 104 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Trap Sources 37 External Clock Timing Characteristics 181 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 182 Type C Timer 182 Type C Timer 182
EElectrical Characteristics163AC173DC164Enabling and Setting Up UART101Setting Up Data, Parity and Stop Bit Selections101Enabling the UART101Equations103ADC Conversion Clock129Baud Rate103Bit Clock Frequency121COFSG Period119Serial Clock Rate96Time Quantum for Clock Generation113Errata7Exception Sequence37External Clock Timing Characteristics174Type A, B and C Timer181External Clock Timing Requirements174Type B Timer182Type C Timer182External Interrupt Requests39
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 181 Type B Timer 182 Type C Timer 182 Type C Timer 182 External Interrupt Requests 39
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Trap Sources 37 External Clock Timing Characteristics 7 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 182 Type C Timer 182 Type C Timer 182 External Interrupt Requests 39 F 5
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Enabling the UART 101 Equations 102 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 174 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 182 Type C Timer 182 Type C Timer 182 Fe Fast Context Saving 39
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 164 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Trap Sources 37 External Clock Timing Characteristics 7 Type A, B and C Timer 181 Type A Timer 181 Type A Timer 182 Type C Timer 182 Type C Timer 182 External Interrupt Requests 39 Fast Context Saving 39 Flash Program Memory 47
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 101 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 37 External Clock Timing Characteristics 37 External Clock Timing Requirements 174 Type A, B and C Timer 181 Type A Timer 182 Type C Timer 182 External Interrupt Requests 39 F Fast Context Saving 39 Flash Program Memory 47
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 101 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Trap Sources 37 External Clock Timing Characteristics 181 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 182 Type C Timer 182 Type C Timer 182 F Fast Context Saving 39 Flash Program Memory 47 I I 10
EElectrical Characteristics163AC173DC164Enabling and Setting Up UART101Setting Up Data, Parity and Stop Bit Selections101Enabling the UART101Equations102ADC Conversion Clock129Baud Rate103Bit Clock Frequency121COFSG Period119Serial Clock Rate96Time Quantum for Clock Generation113Errata7Exception Sequence7Trap Sources37External Clock Timing Characteristics174Type A, B and C Timer181External Clock Timing Requirements174Type C Timer182Type C Timer182Type C Timer182FFast Context Saving39FFast Context Saving39II10I/O Ports57
E Electrical Characteristics 163 AC 173 DC 164 Enabling and Setting Up UART 101 Setting Up Data, Parity and Stop Bit Selections 101 Equations 101 ADC Conversion Clock 129 Baud Rate 103 Bit Clock Frequency 121 COFSG Period 119 Serial Clock Rate 96 Time Quantum for Clock Generation 113 Errata 7 Exception Sequence 7 Trap Sources 37 External Clock Timing Characteristics 174 Type A, B and C Timer 181 External Clock Timing Requirements 174 Type A Timer 182 Type C Timer 182 Type C Timer 182 Fast Context Saving 39 Flash Program Memory 47 I I/O Ports 57 Parallel (PIO) 57

Slot Enable Bits Operation with Frame Sync...... 122

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